

# **Advance Product Change Notification**

Issue Date: 01-Aug-2019

Dear Emma Tempest,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.

## 201907002A



#### **Management Summary**

Bump site release of Chipbond-KF (plated bump) for product types in fcQFN (SOT1232)

**Change Category** 

[] Wafer Fab Process	[X] Assembly Process	[] Product Marking	[] Test Location	[] Design
[] Wafer Fab Materials	[X] Assembly Materials	[] Mechanical Specification	[]Test Process	[] Errata
[] Wafer Fab Location	[X] Assembly	[] Packing/Shipping/Labe	[] Test ling Equipment	•
[] Firmware	Location [] Other			coverage

Bump Site Transfer ASE-KH (Printed Bump) to Chipbond-KF (Plated Bump) for Products in SOT1232 (fcQFN)

## **Description of Change**

Bump site release of plated bump process of Chipbond-KF for product types in fcQFN (SOT1232). Reason for Change

Release of plated bump technology is required in view of supply contingency and out phasing of present printed bump process technology.

## **Identification of Affected Products**

Product identification does not change

#### **Product Availability**

#### Sample Information

Samples are available from 11-Oct-2019

#### **Production**

Planned first shipment 17-Feb-2020

#### Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

#### **Data Sheet Revision**

No impact to existing datasheet

## **Disposition of Old Products**

Existing inventory will be shipped until depleted

#### **Additional information**

Affected products and sales history information: see attached file

Self qualification: <u>view online</u>
Additional documents: <u>view online</u>



#### **Timing and Logistics**

The Self Qualification Report will be ready on 29-Nov-2019.

The Final PCN is planned to be issued on: 29-Nov-2019.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 31-Aug-2019.

#### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please <u>contact NXP "Global Quality Support Team"</u>.

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Wali Ahmad

**Position** Pr. Customer Quality PL SAS

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

## NXP Quality Management Team.

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